



Material Content Data Sheet



Sales Product Name		SPD03N50C3		Issued		19. July 2018			
MA#		MA001145360							
Package		PG-TO252-3-313		Weight*		318.20 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.304	0.72	0.72	7240	7240	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.22	46.28	462278	462880	
wire	non noble metal	aluminium	7429-90-5	0.528	0.17	0.17	1659	1659	
encapsulation	organic material	carbon black	1333-86-4	1.414	0.44		4443		
	plastics	epoxy resin	-	24.738	7.77		77745		
	inorganic material	silicondioxide	60676-86-0	115.209	36.21	44.42	362068	444256	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11754	11754	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4464	4475	
solder	noble metal	silver	7440-22-4	0.059	0.02		185		
	non noble metal	tin	7440-31-5	0.047	0.01		148		
	non noble metal	lead	7439-92-1	2.245	0.71	0.74	7056	7389	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60269	60347	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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